0/594221

Docket No. 8007-1116

## IAPO1 Rec'd PCT/PTO 25 SEP 2006

PATENT

## IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Takashi SUEYOSHI et al.

Conf.

Application No. NEW NATIONAL PHASE

Group

Filed September 25, 2006

Examiner

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED PRODUCT THEREOF

## PRELIMINARY AMENDMENT

Assistant Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 September 25, 2006

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

 $\label{lem:Amendments} \textbf{Amendments} \ \ \textbf{to} \ \ \textbf{the Specification} \ \ \textbf{begin on page 2 of this}$   $\ \ \textbf{paper.}$ 

Amendments to the Claims are reflected in the listing of claims which begin on page 3 of this paper.

Remarks begin on page 5 of this paper.

An Appendix is attached following the signature page of this paper.